

PATENT

MERIE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chopra et al.

Serial No.: 10/620,002

Filed: July 14, 2003

For: SLURRY FOR USE WITH FIXED-ABRASIVE POLISHING PADS IN POLISHING SEMICONDUCTOR DEVICE CONDUCTIVE STRUCTURES THAT INCLUDE COPPER AND TUNGSTEN

Confirmation No.: 7481

Examiner: L. Umez-Eronini

Group Art Unit: 1765

Attorney Docket No.: 2269-4373.2US

(00-0036.02/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or exclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 2213-1450.

October 23, 2006

Signature

Erika Gandre
Name (Type/Print)

Do Not Enten

Amendment

entered per RCE filed 12/4/04

L.J.WE

11/16/2006

RESPONSE TO FINAL OFFICE ACTION

Mail Stop Amendment Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Sir:

This Response follows the final Office Action of August 21, 2006, the shortened statutory period for response to which expires on November 21, 2006. This Response is being submitted within two months of the mailing date of the Final Office Action.